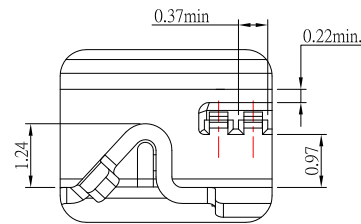
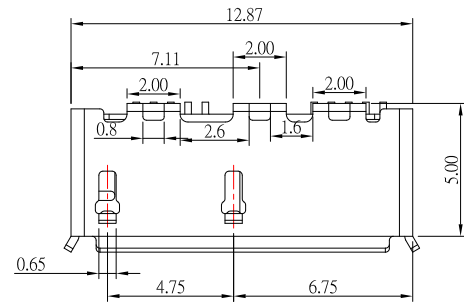




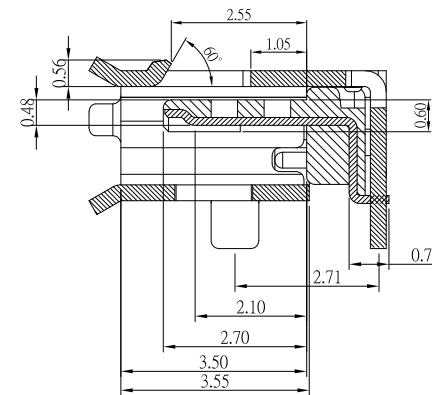
MRUSB-10BD1B-30x-S277

鍍層厚度:

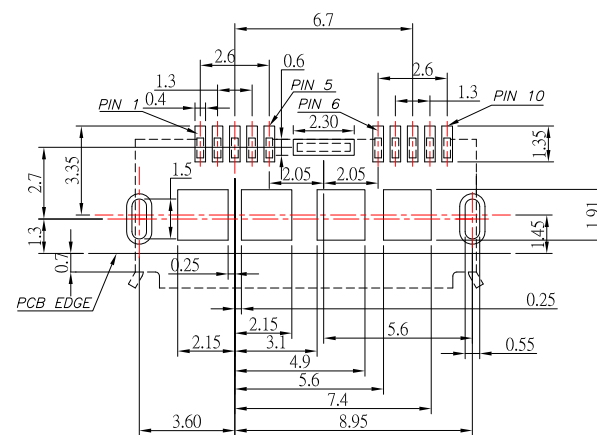
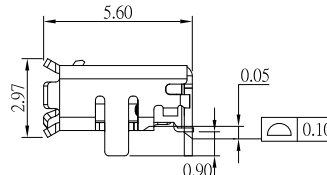
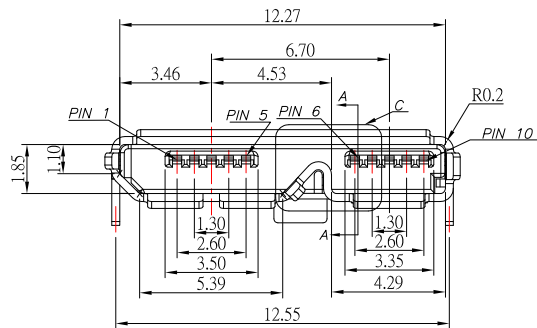
Blank : 1u"
2 : 15u"
3 : 30u"



Detail C (2:1)



SECTION "A-A"(2:1)



P.C.B LAYOUT MOUNTING PATTERN

Pin Number	Signal Name
1	VBUS Power
2	D-
3	D+
4	ID
5	GND
6	MicB_SSTX-
7	MicB_SSTX+
8	GND_DRAIN
9	MicB_SSRX-
10	MicB_SSRX+

NOTE:

1.MATERIAL:

- 1.1 INSULATOR: LCP, UL 94V-0,Black
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS304

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	新增pcb layout尺寸及更新外觀距離尺寸	Jack	031815
2	新增pin定義及新增尺寸	Jack	031715
1	新增pin定義	Jack	031315

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/18/15			
CHECKED BY:	DATE	FINISH	MODLE	MICRO 3.0 B/F DIPX3 , 腳長:0.9mm
Jacky Chen	03/18/15			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-10BD1B-30x-S277
Tony Kao	03/18/15	1 : 1		
SHEET NO.	1 of 1	PART NO.	MRUSB-10BD1B-30x-S277	SIZE A4
				VER R3